WDFN12 3.5x3, 0.5P
CASE 511DK
ISSUE O

DATE 31 AUG 2016

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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NOTES:
A. CONFORMS TO JEDEC MO-229
VARIATION WFED-2.
B. DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS AND TOLERANCES PER
ASME Y14.5M, 1994
D. LANDPATTERN RECOMMENDATION IS
BASED ON IPC 7351 DESIGN GUIDELINES
E. LANDPATTERN EXTENSION TO INCLUDE
CENTER PAD TABS IS OPTIONAL